



# SUPERAPEX CORPORATION

[www.superapexco.com](http://www.superapexco.com)

# Company Background

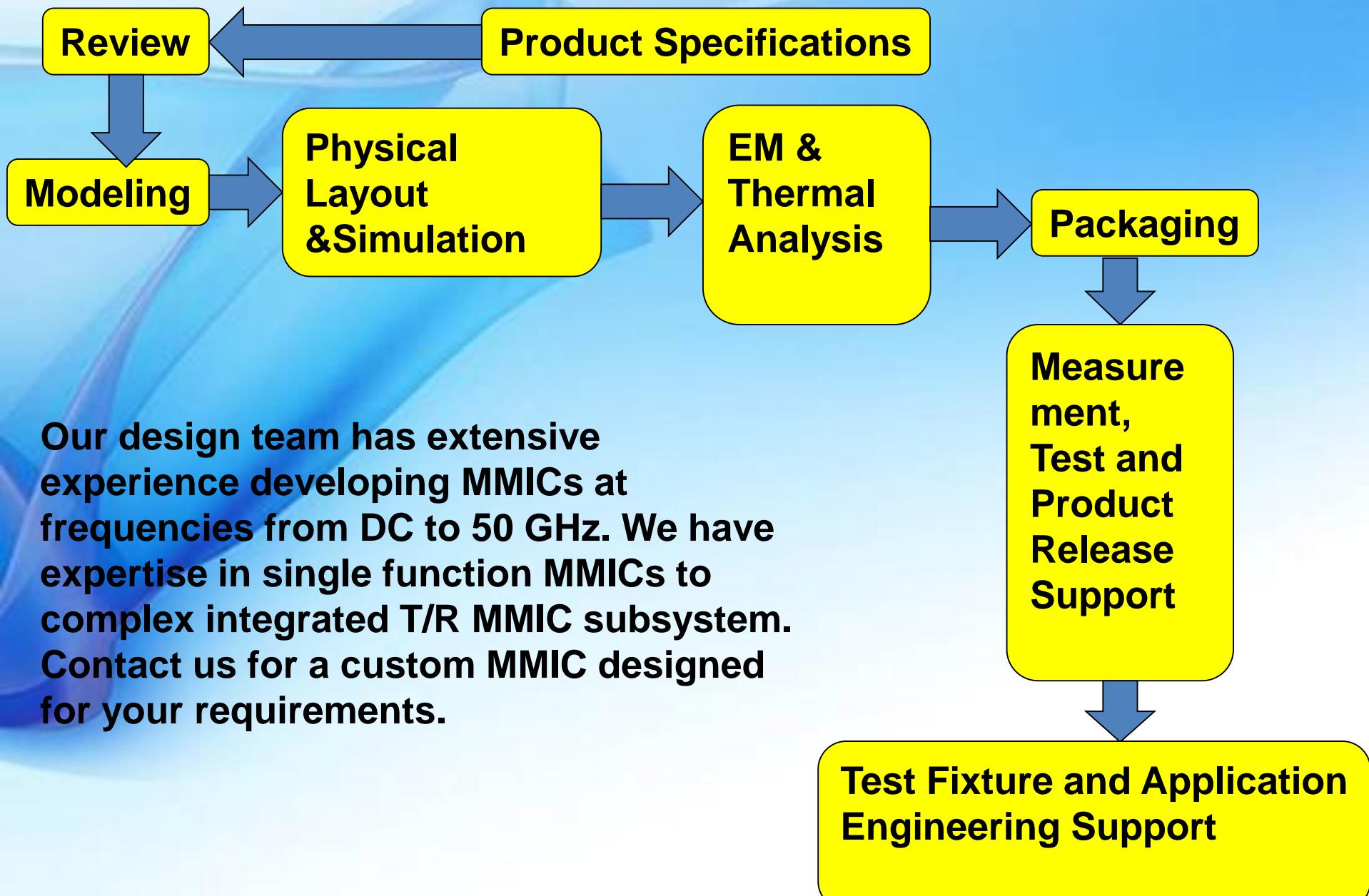


**SuperApex Corporation is a microwave & RF company located in Chicago, USA. We provide the innovative solutions, products and services for our customers around the world. The company provides GaAs MMIC products, RF/Microwave/Millimeter-wave modules and chip packaging solutions. We have completely proprietary intellectual property rights for all the products we design and manufacture. SuperApex works with our customers from feasibility contracts through to new product introductions and supply. The company prides itself on working closely with its clients and developing long-term partnerships which offers success to all parties.**

# What are we able to do ?

- 1) Expertise in the design & development of components and subsystems.
- 2) RF, Microwave and Millimeter wave markets.
- 3) DC-50GHz: RF, microwave & mm-wave.
- 4) Multi-technology: GaAs and GaN.
- 5) MMICs, packaging, modules, sub-systems.

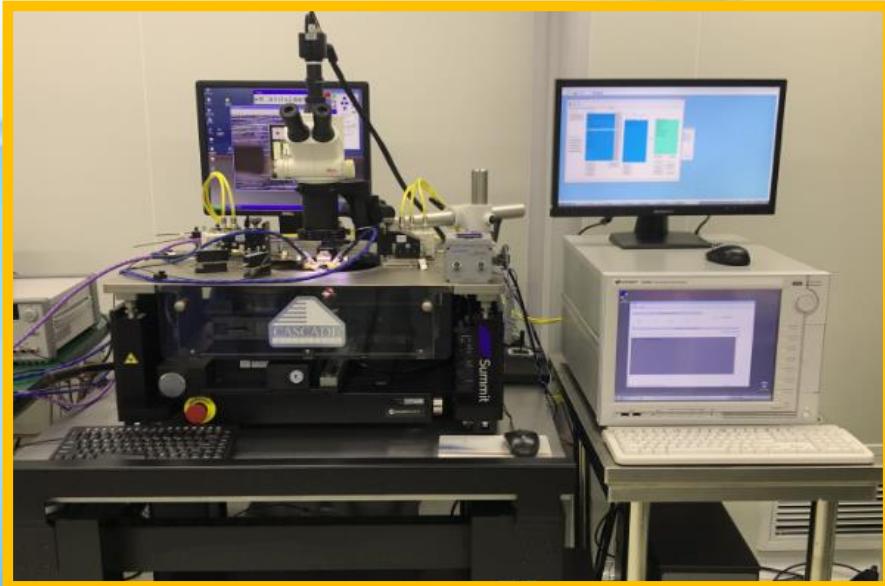
# MMIC Product Development Cycle



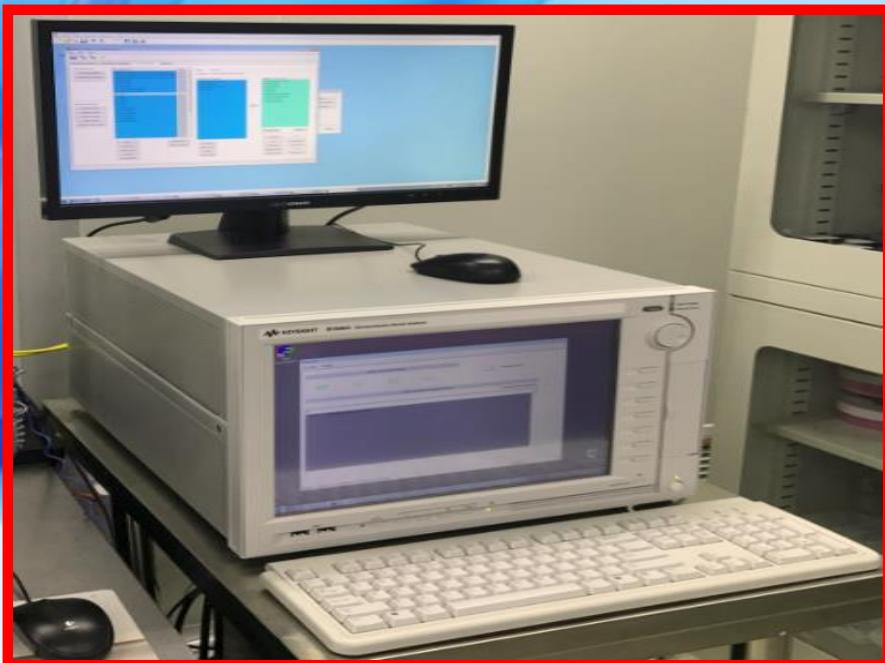
# **MMIC Design Flow**

- 1) Product Specifications**
- 2) Physical Layout and Simulation**
- 3) Electromagnetic Analysis and Thermal Analysis**
- 4) Packaging**
- 5) Measurement, Test and Product Release Support**
- 6) Test Fixture and Application Engineering Support**

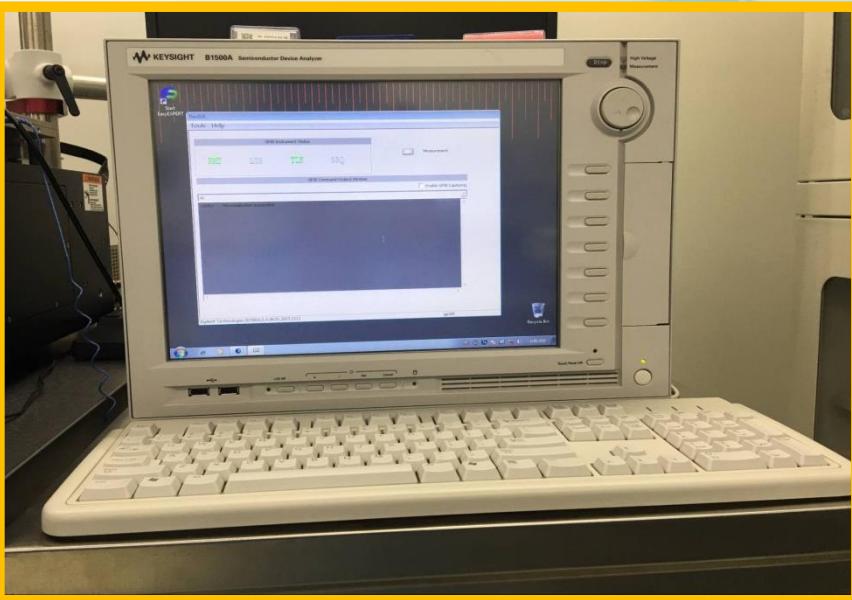
# Modeling



**B1500A + IC-CAP  
to optimize  
foundry PDKs**

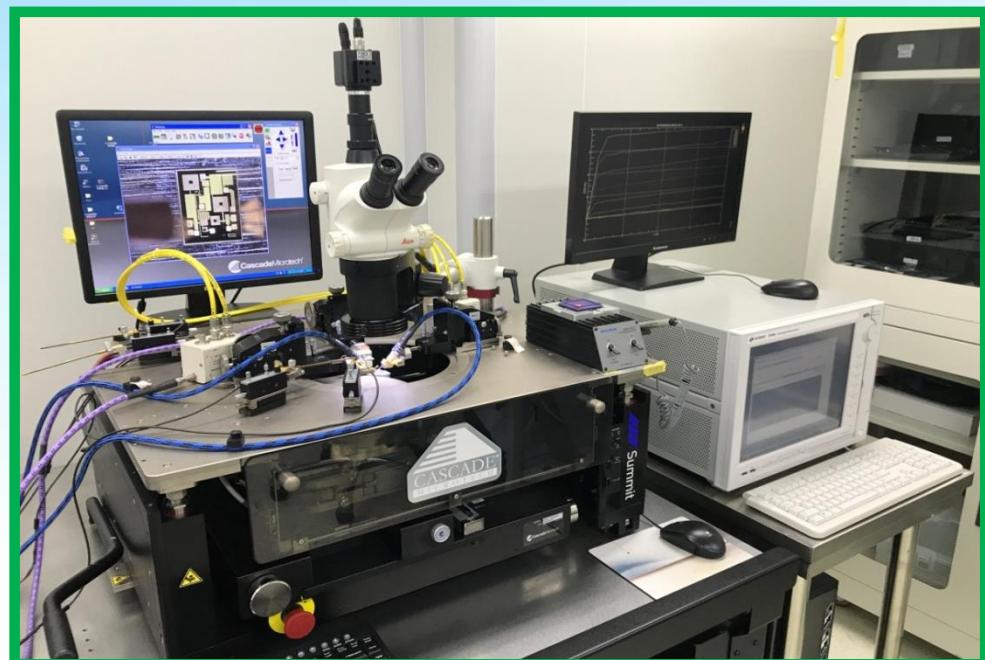


# Modeling Facilities



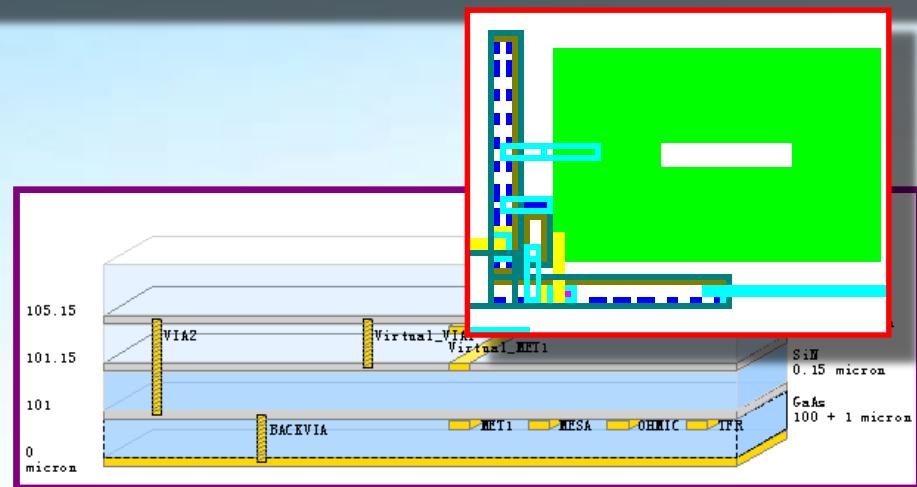
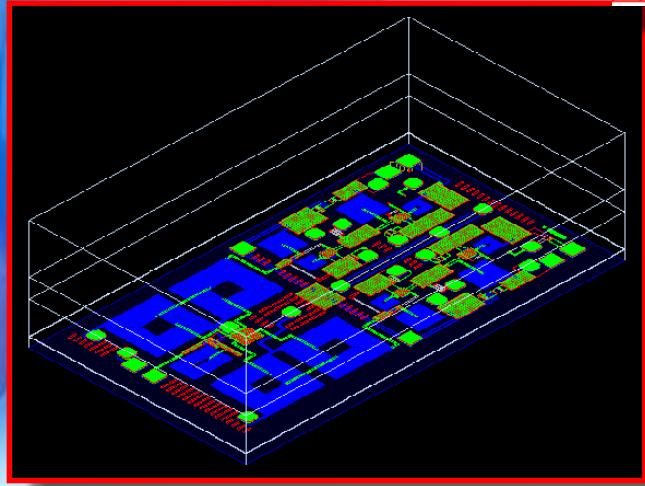
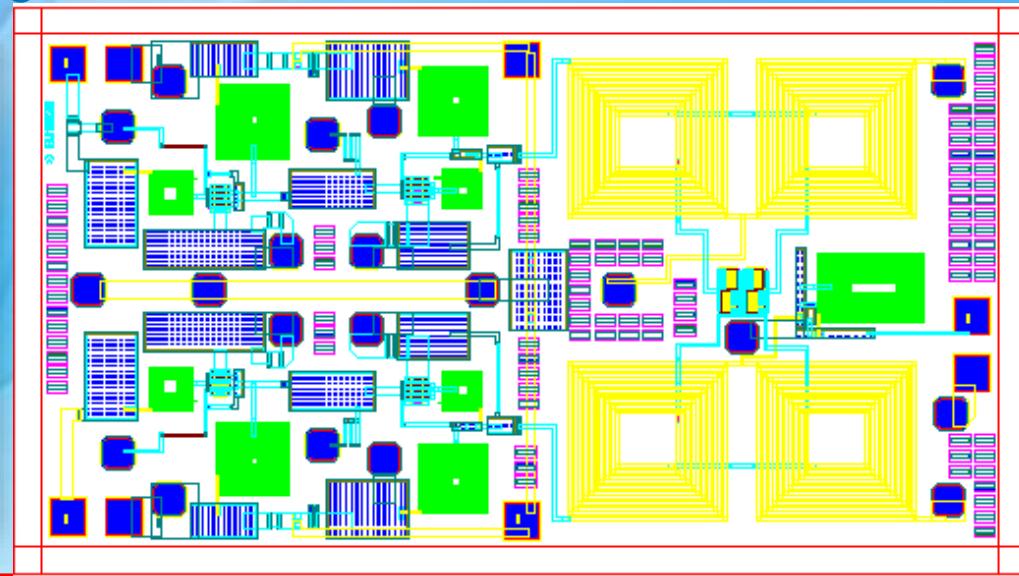
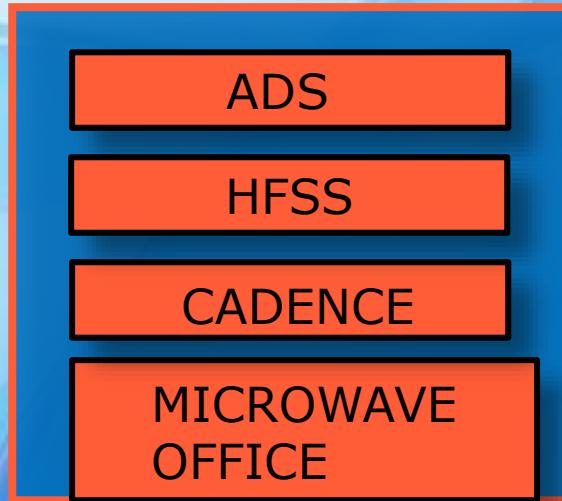
**B1500A**

**Modeling Platform**

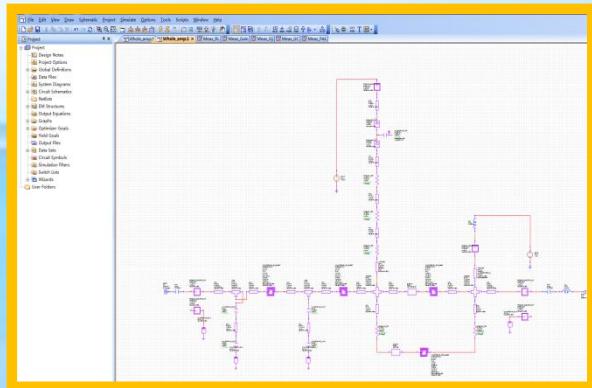


# Simulation Platform

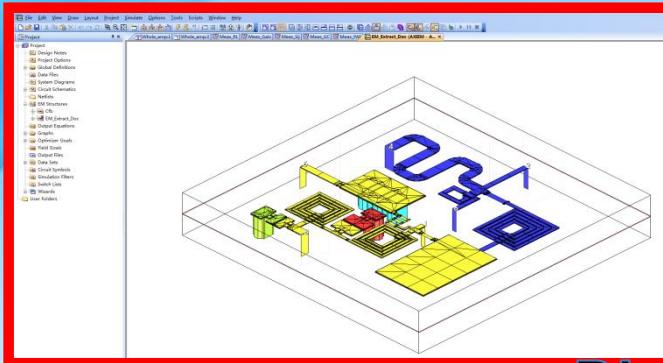
## Design Software



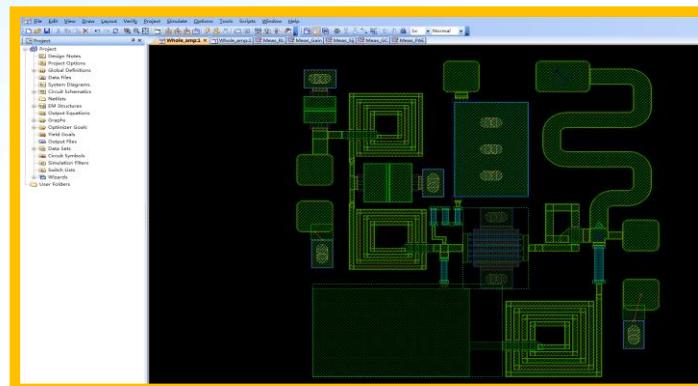
# Schematic Simulation



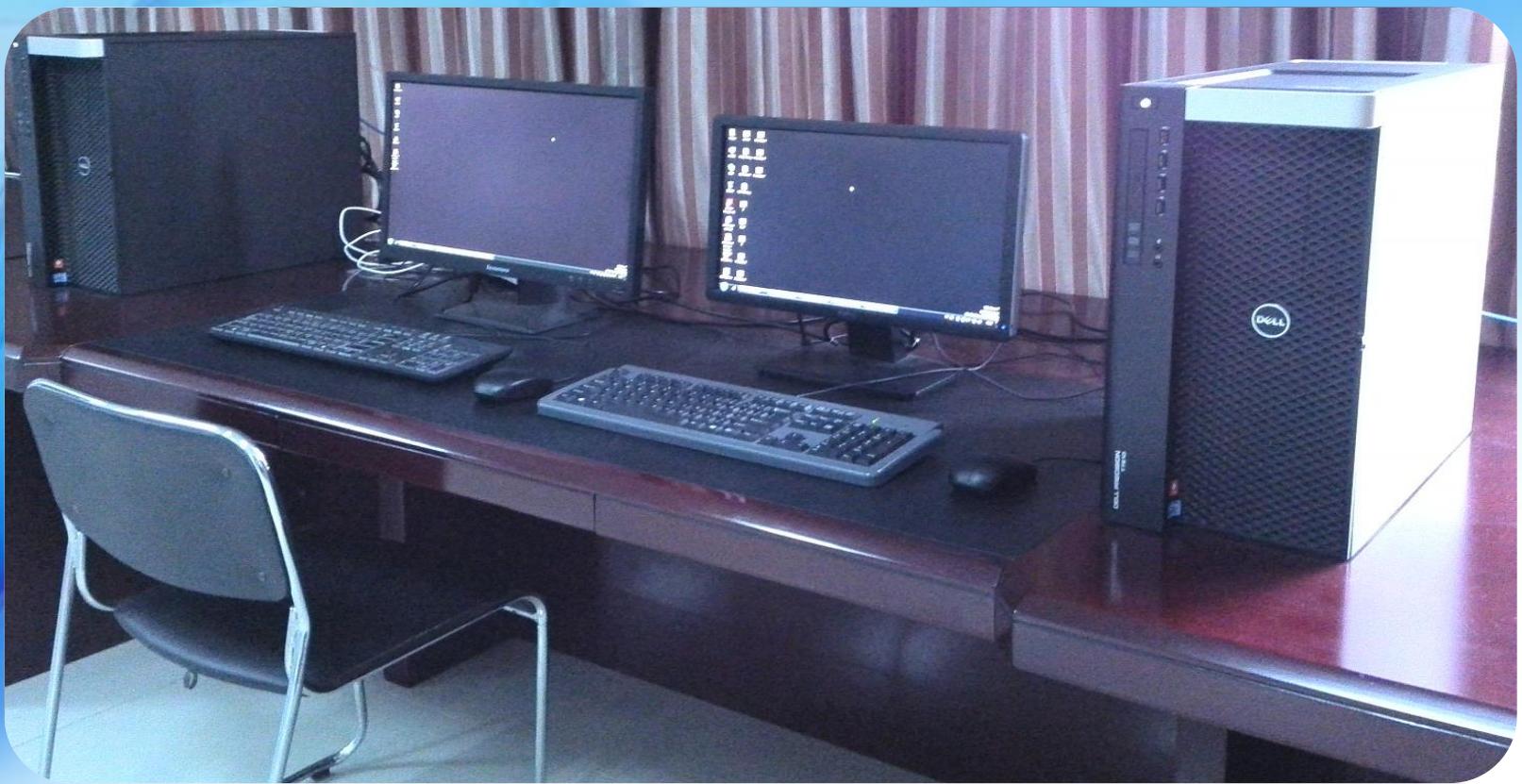
## EM Simulation



## Physical Layout



# High Performance Workstations and Servers for MMIC Design



# Foundry Service Providers



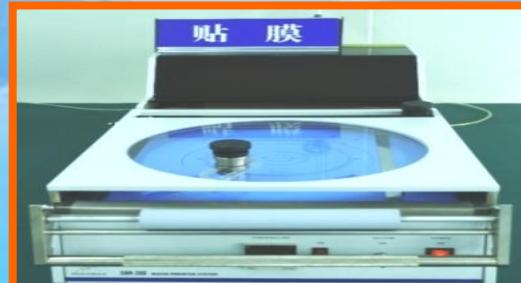
We leverage all the  
commercially available foundry  
service providers worldwide

# Wafer Processing after Fabrication from Foundry

Wafer Test



Wafer Foil



Dicing



Wafer Processing Facility



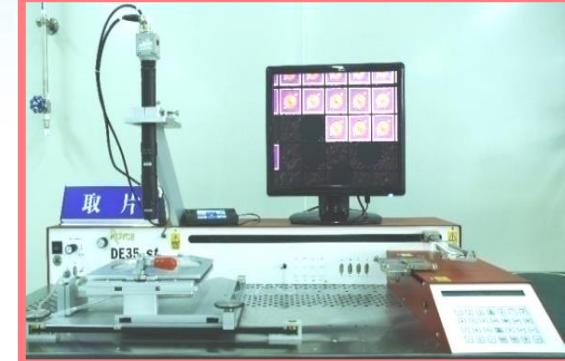
Cleaning



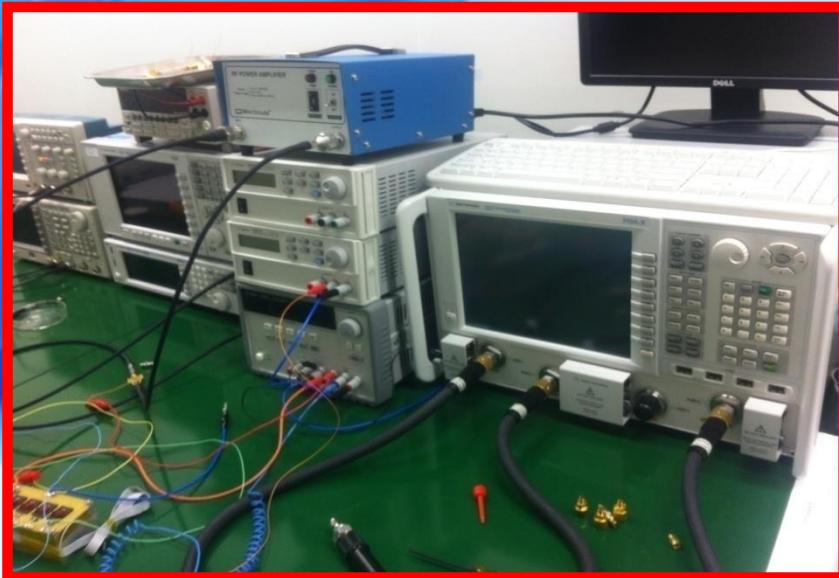
Exposure



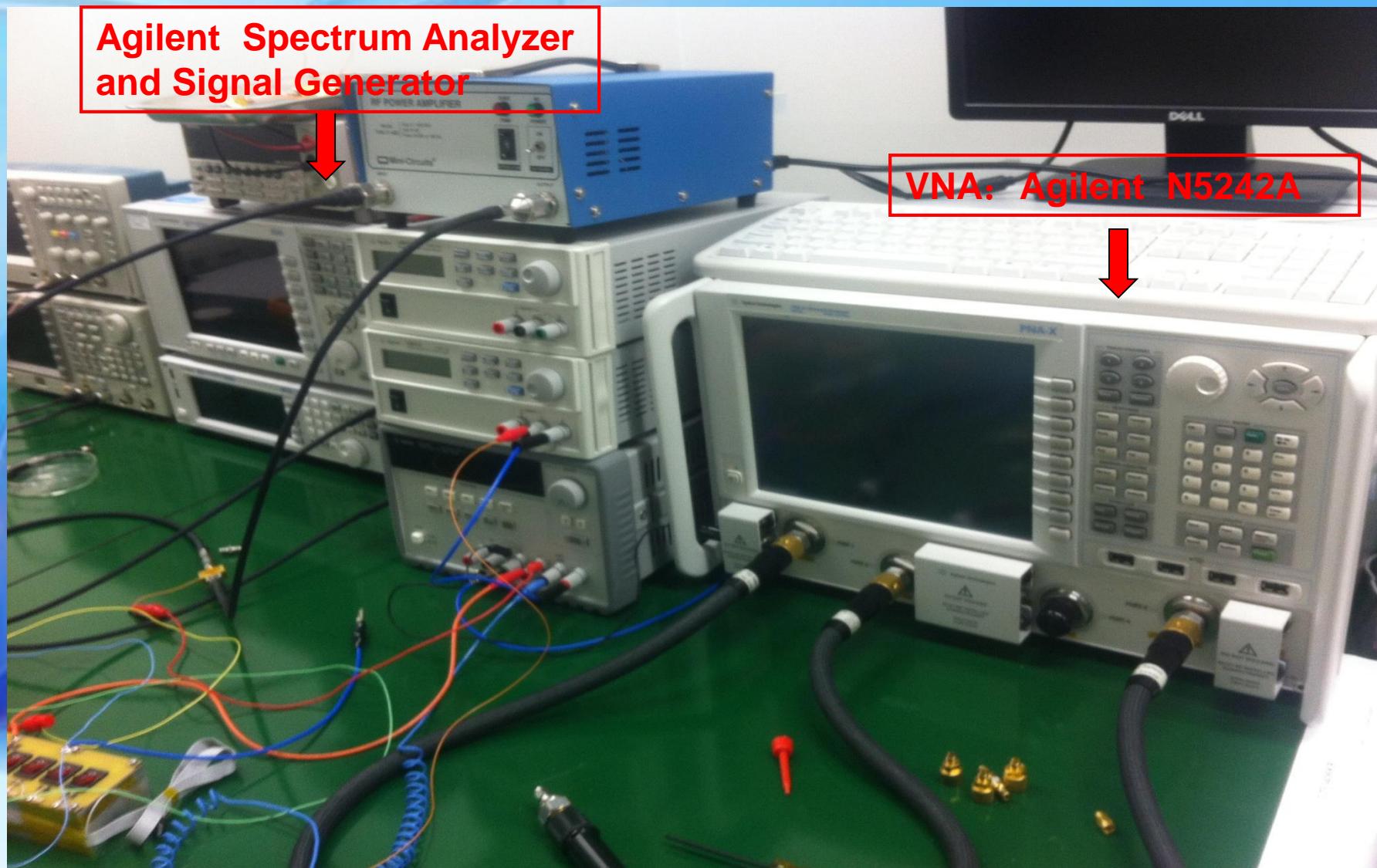
Die Pick-Up



# MMIC Test Equipment



# Some Major Test Equipment II



# Wafer Probing Station

**Cascade Summit12000**

**Summit**

200 mm Semi-automatic  
Probe System

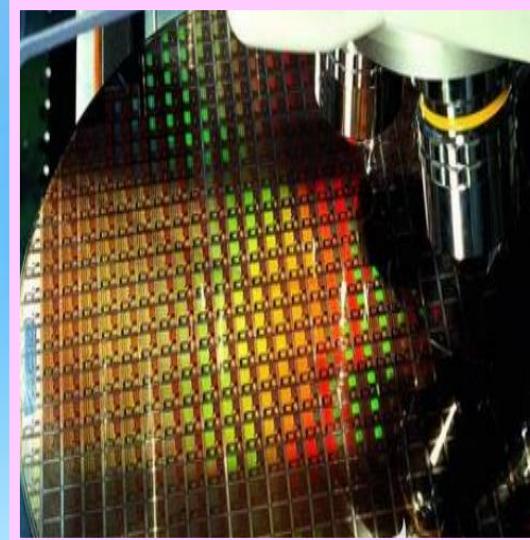
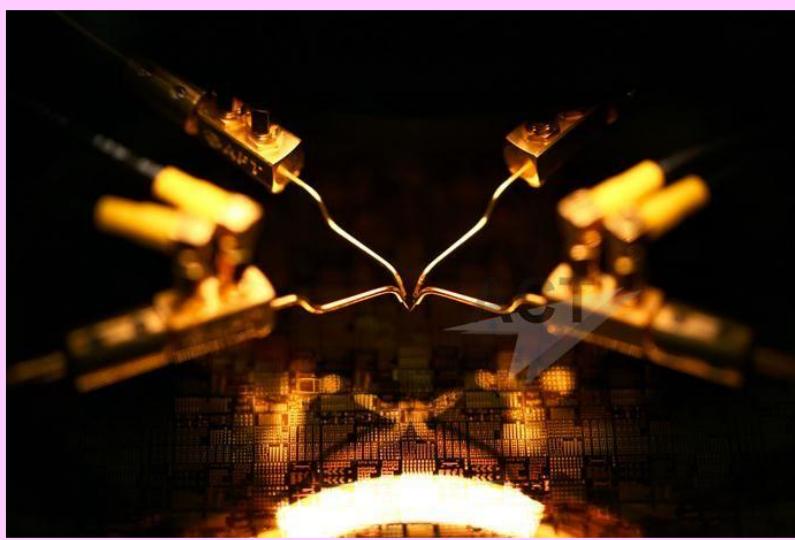


On-wafer test

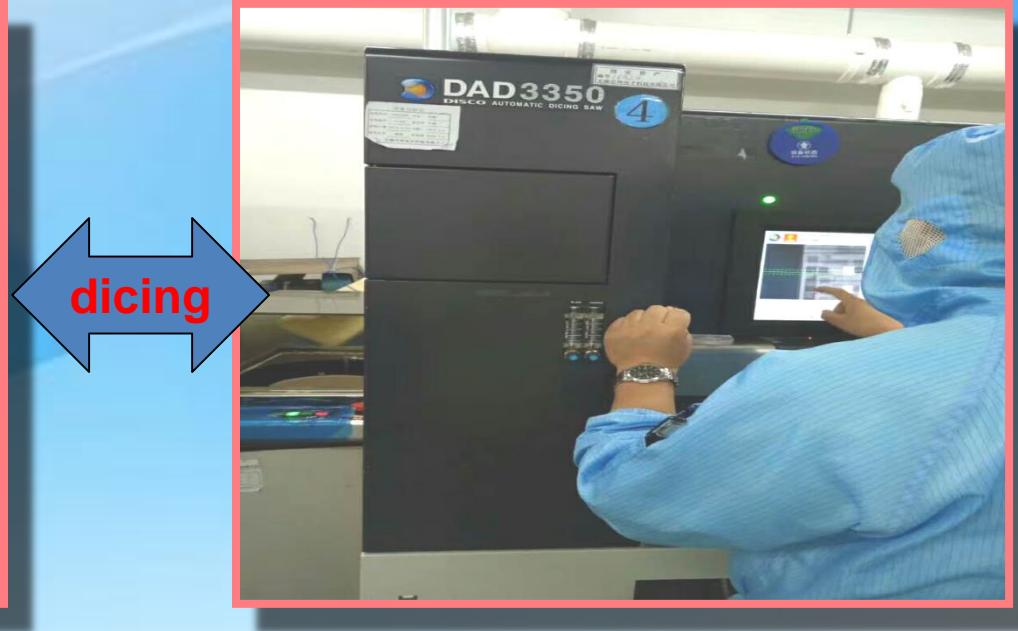
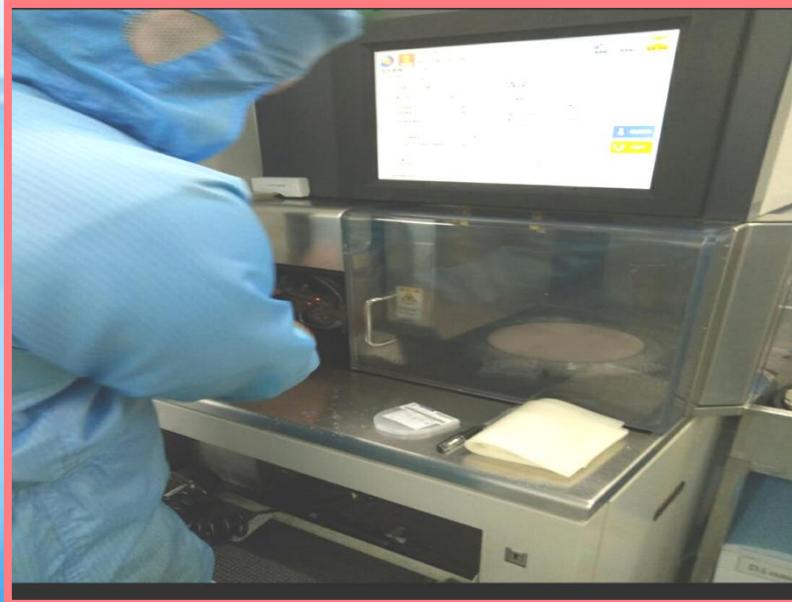


Die chip test

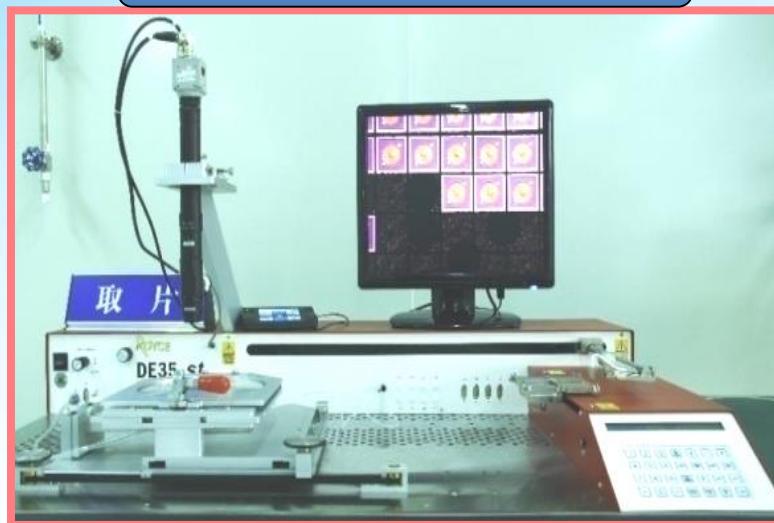
# Wafer & Chip Test Facility



# Dicing and Die Pick-Up Facility

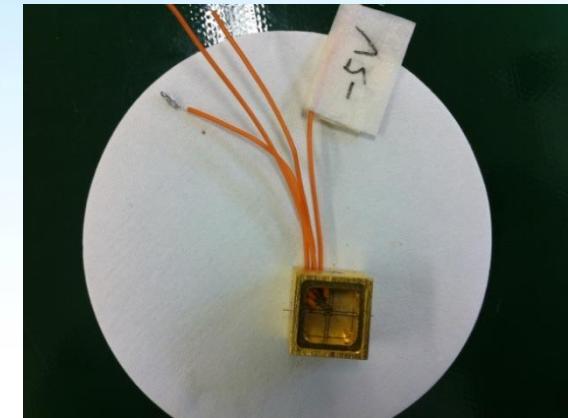
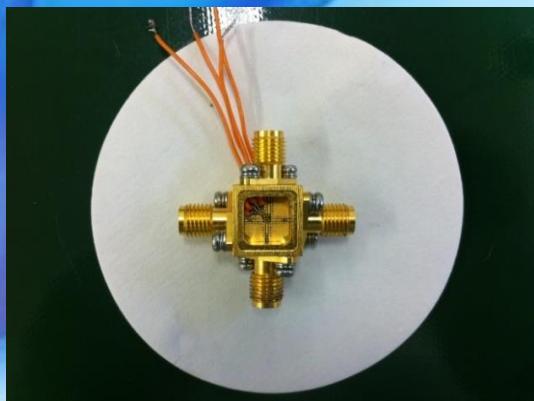
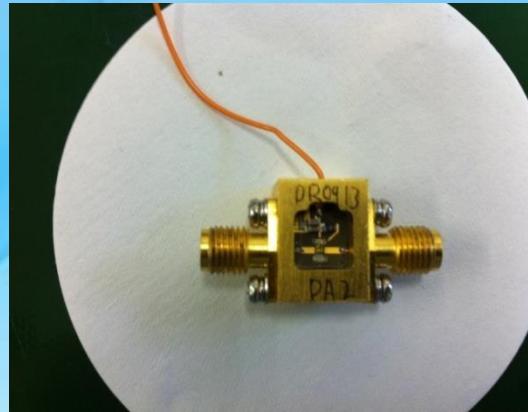


Automatic die pick-up



# Reliability and Environmental Test

Use the test fixture to simulate all kinds of product real life tests including extreme temperatures, thermal shock, vibration, aging and ESD, etc. per MIL STD.

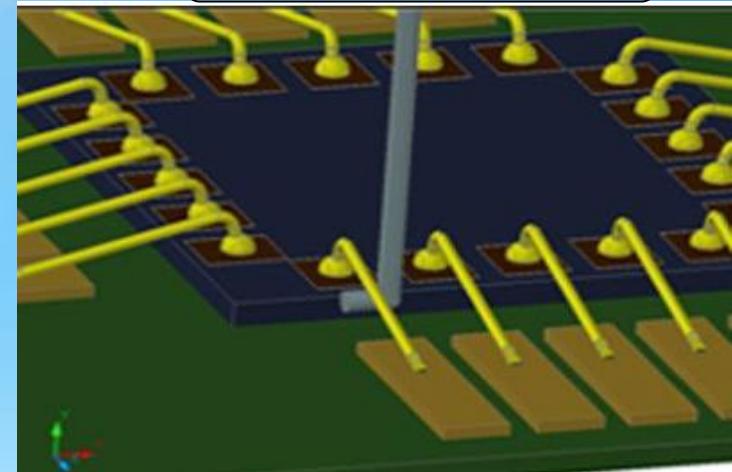


# Reliability Test Facility

High/Low Temperature



Shear Strength Test



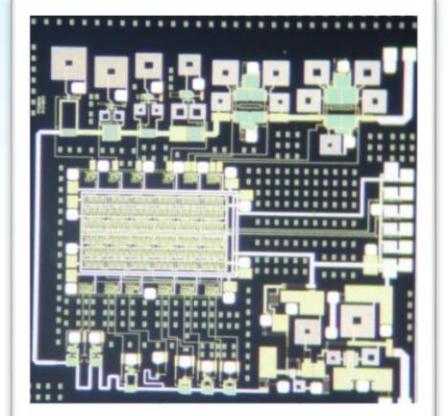
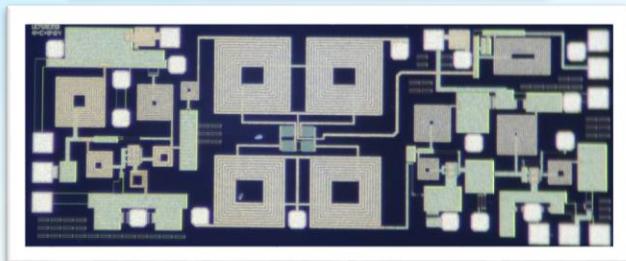
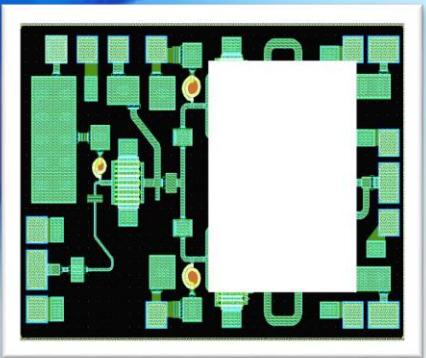
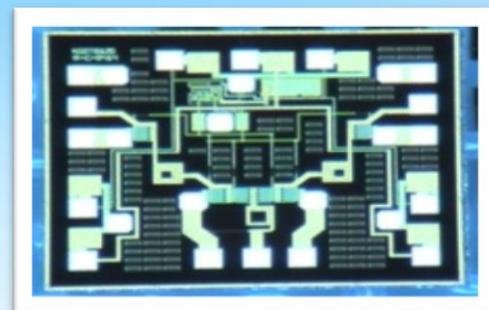
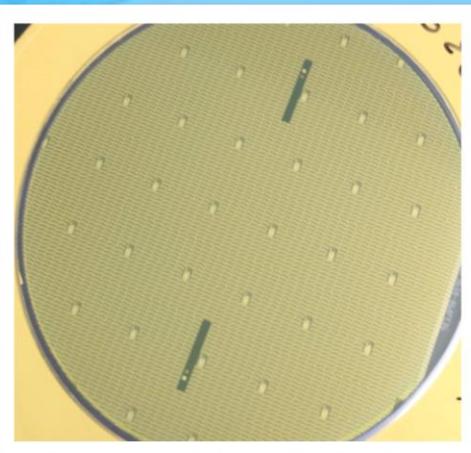
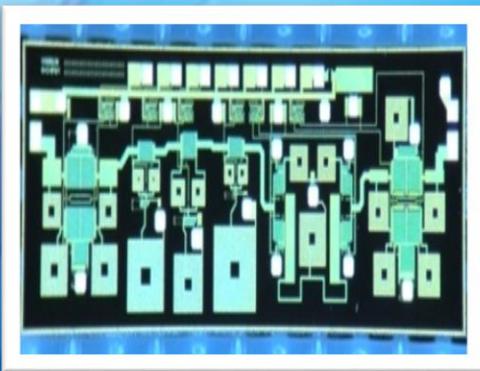
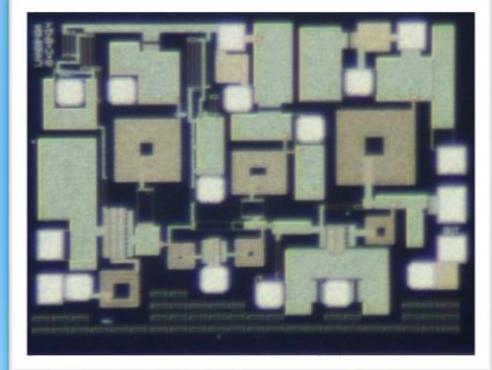
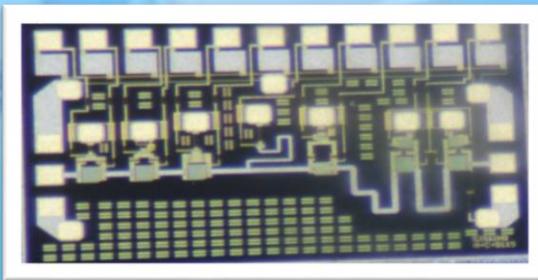
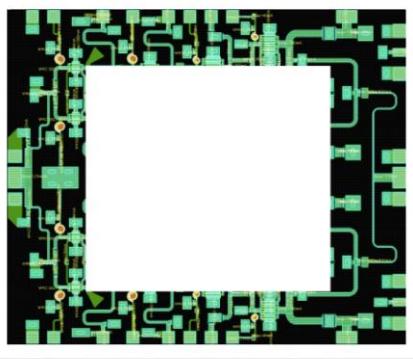
Aging Test



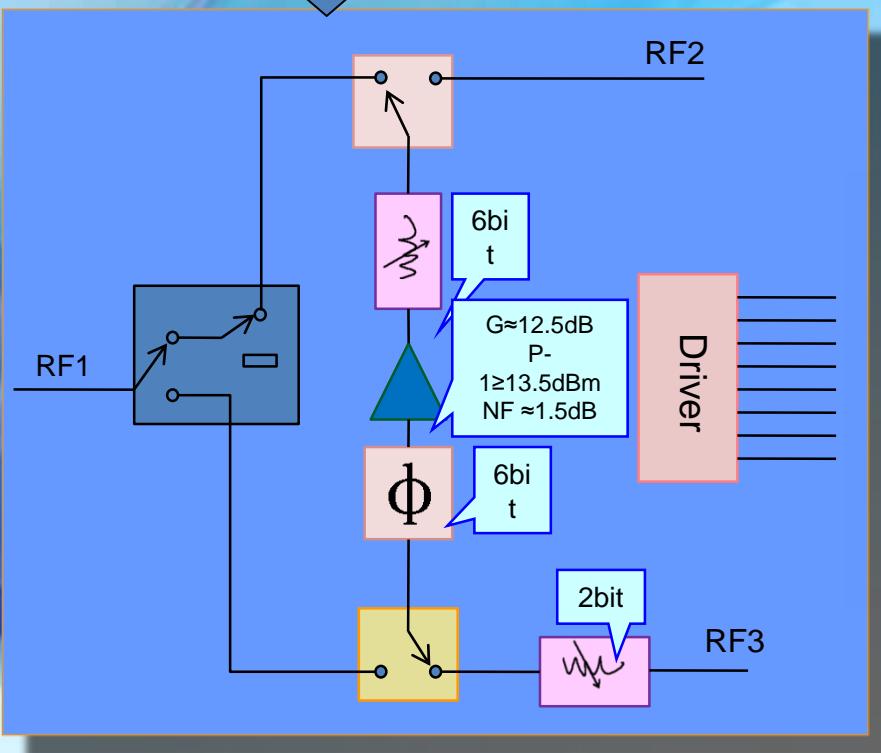
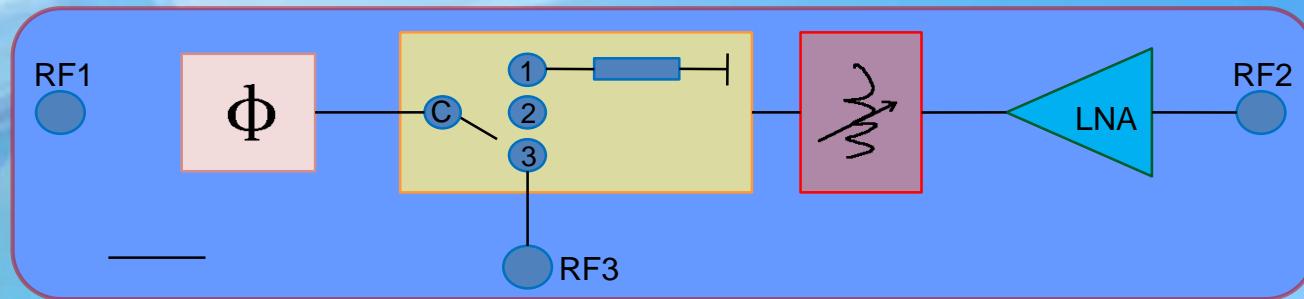
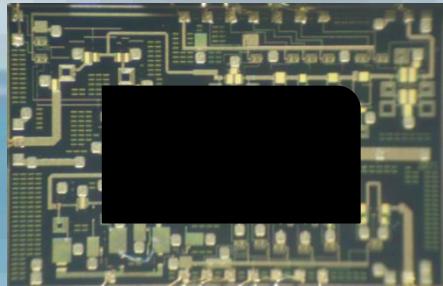
ESD Test



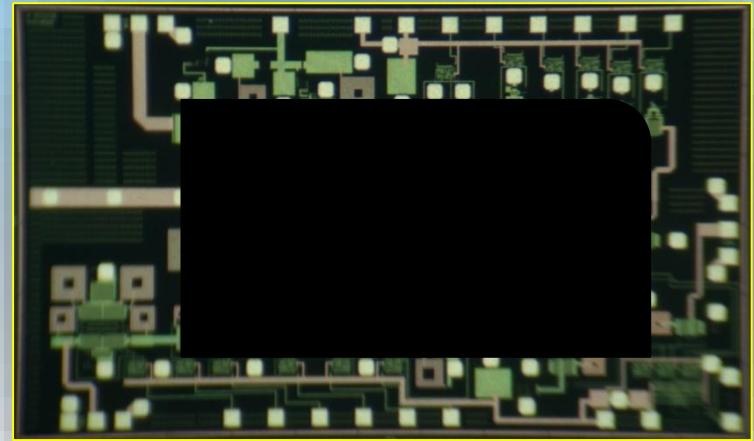
# Our GaAs MMIC Products Cover Standard T/R chips from P, L, S, C, X, Ku, K to Ka Band



# GaAs Multi-Function Core Chips

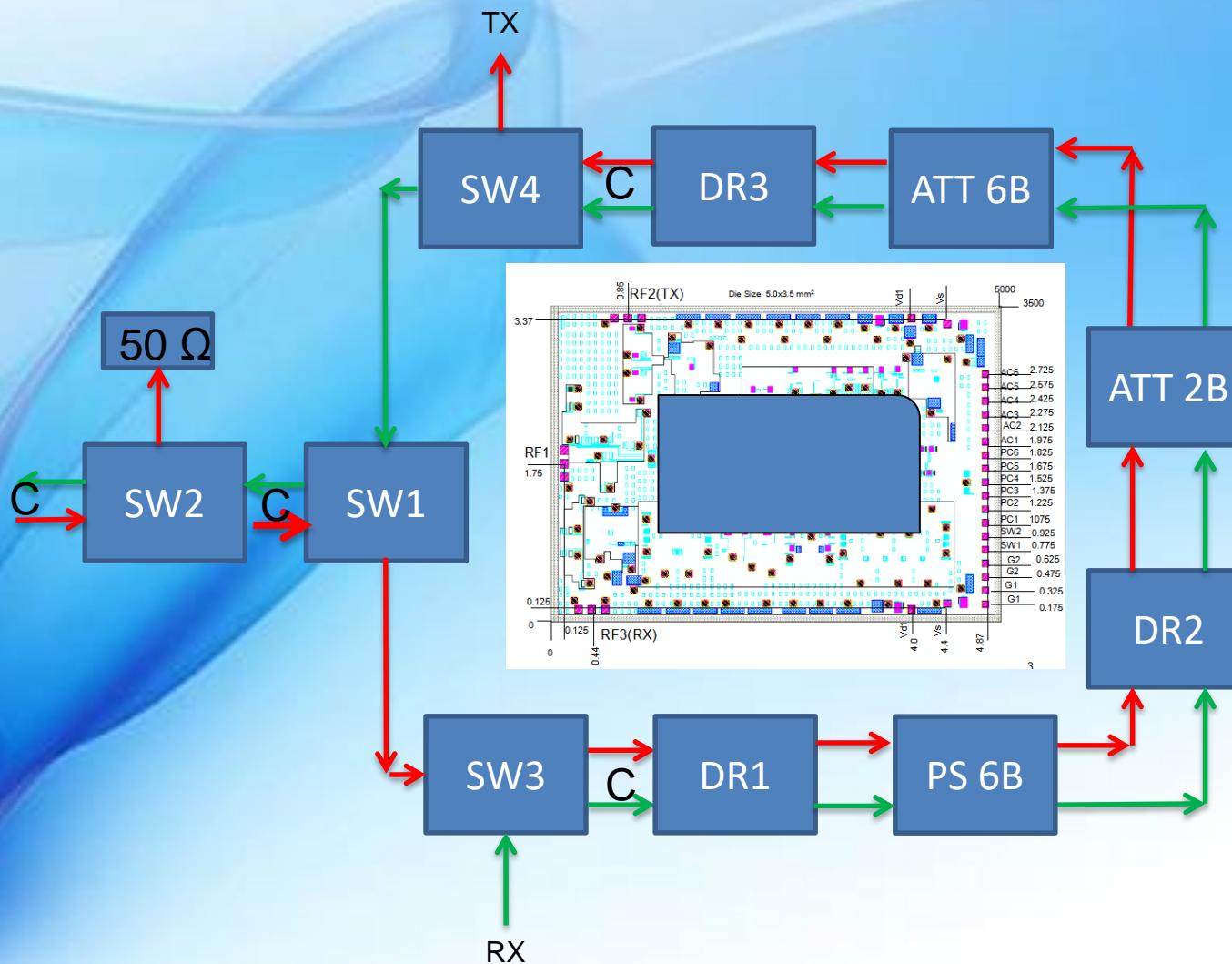


X Band MFC Core Chip



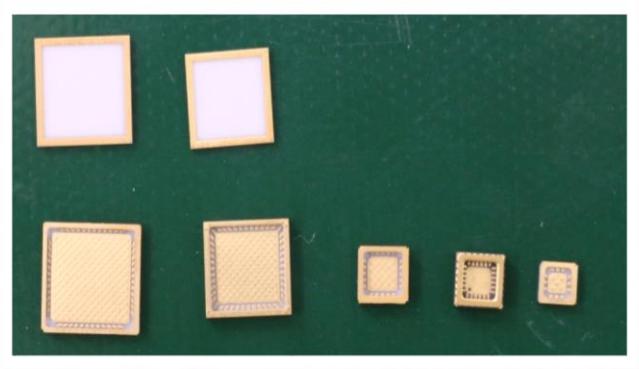
S Band MFC Core Chip

# GaAs MFC Core Chip

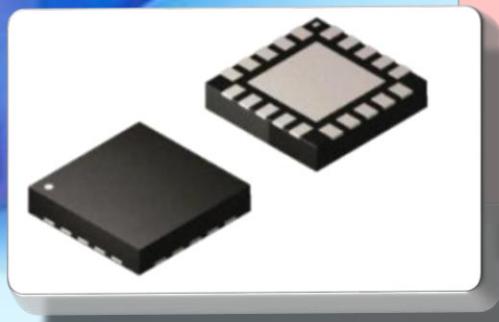


X Band MFC Core Chip

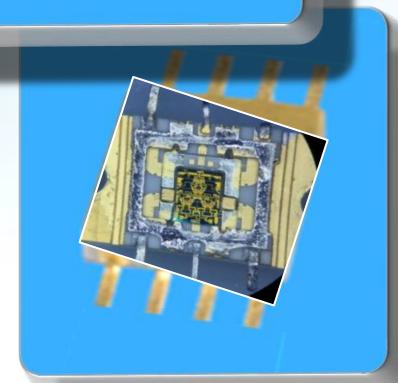
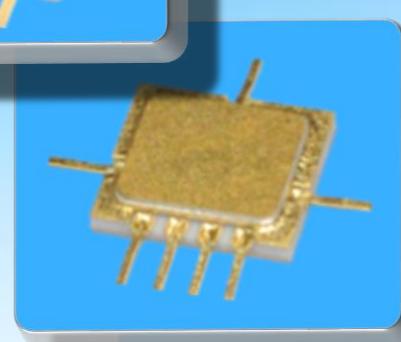
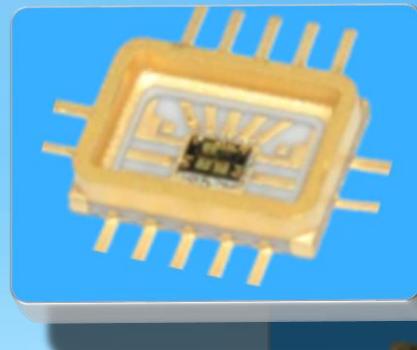
# MMIC Metal, Ceramics and Plastic Packaging



3X3、4X4、5X5、6X6、7X7、  
8X8 Metal Ceramics SMD  
QFN Packages



Plastic SMD QFN Packages



High Power Metal  
Ceramics Packages

# Major Products in Development in 2019 and Beyond

## 1) SATCOM Products

- a. Driver Amplifiers ( Bare Die + QFN Packaged Chips )
- b. Power Amplifiers ( Bare Die + QFN Packaged Chips )
- c. Ku and Ka LNA for LNB
- d. Up and Down Converters
- e. Some GaN PAs and Switches in the near future

## 2) 5G Products

- a. 28GHz and 38GHz T/R Integrated Chips as FEM
- b. 28GHz and 38GHz PA

## 3) Test and Measurement Products

- a. DC~ 60/70/80 GHz Distributed Broadband Amplifiers
- b. Dc~70/80/90/100 GHz Power Detectors

# New Products being Planned in the near future

1. Wideband Distributed Amplifiers
  - DC ~ 6GHz, P1dB = 27 dBm (0.5W)
  - DC ~ 6GHz, P1dB = 30 dBm (1W)
  - DC ~ 6 GHz, Gain=13dB, P1dB=23dBm
  - DC ~ 40GHz, P1dB = 13 dBm
  - DC ~ 67GHz, P1dB = 11 dBm
  - DC ~ 90GHz, P1dB =10 dBm
2. Wideband Low Noise Amplifiers
  - 20MHz ~ 8GHz, NF=1.3dB maximum, Gain=26dB
  - 20MHz ~ 12GHz, NF=1.5dB maximum
3. Wideband Switches
  - DC ~ 40GHz SPST , GaAs Technology
  - DC ~ 67GHz SPST, GaAs Technology
  - DC ~ 50GHz SP2T, Low Insertion Loss, VPIN Technology
  - DC ~ 50GHz SP3T, Low Insertion Loss, VPIN Technology
  - DC ~ 40GHz SP4T, VPIN Technology
  - DC ~ 67GHz SP2T, VPIN Technology

# 5-70GHz Power Detector

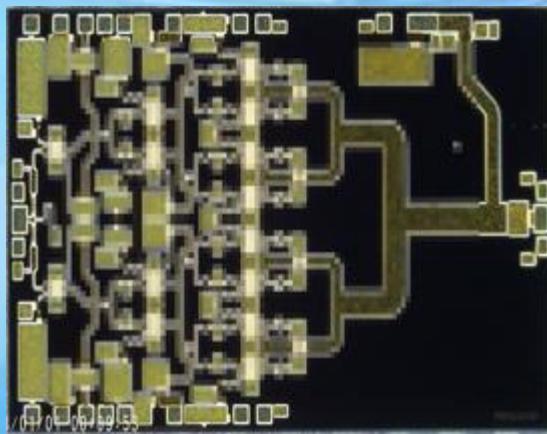
Product Overview	
Frequency	5-70GHz
Flatness	2dB
Dynamic Range	30dB
Maximum Input Power	13dBm
Input Return Loss	-10dB

# 10-100GHz Power Detector

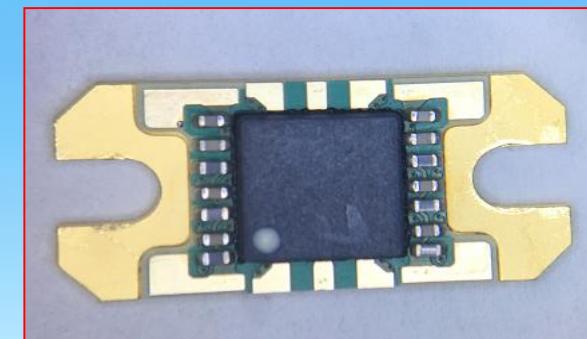
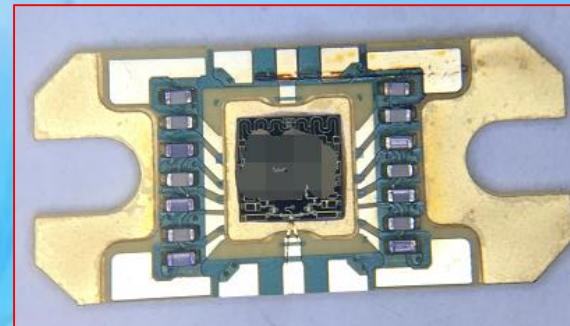
Product Overview	
Frequency	10-100GHz
Flatness	2dB
Dynamic Range	30dB
Maximum Input Power	10dBm
Input Return Loss	-10dB

# SATCOM Products in Ku and Ka Band

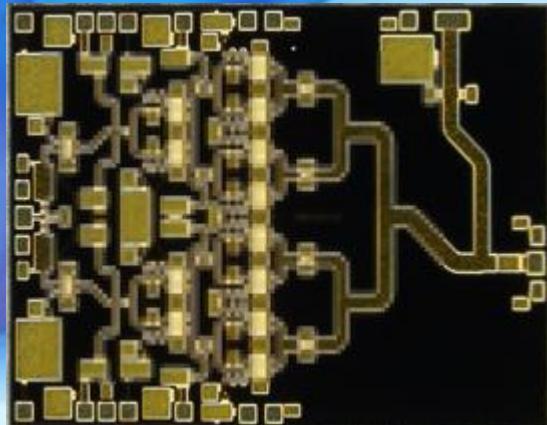
18-26GHz 1.5w PA



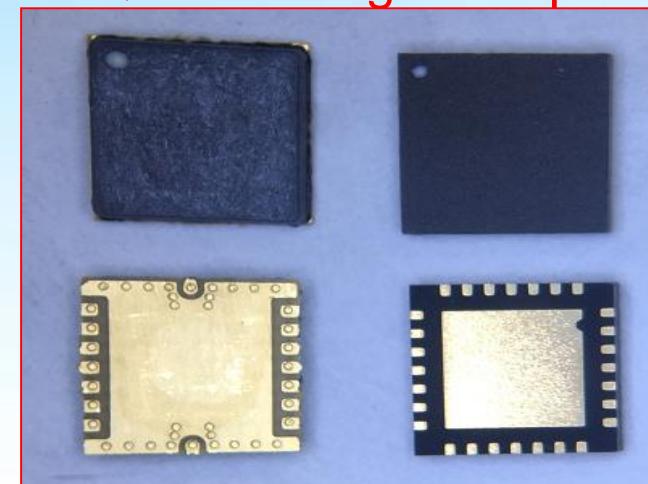
Carrier Form package



27-33GHz 2w PA



QFN Packaged Chips



# SuperApex Currently Existing Products for T & M

## 1. Power Detectors

- SAC1001Q3: DC ~ 20 GHz, Dynamic Range = 30 dB
- SAC1002: 1 ~ 40 GHz, Dynamic Range = 30 dB

## 2. Wideband Distributed Amplifiers

- SAC3045: 2 ~ 20 GHz, NF = 3 dB, Gain = 16 dB, P1dB = 14 dBm
- SAC3051Q5: DC ~ 22 GHz, NF = 3 dB, Gain = 16 dB, P1dB = 14 dBm
- SAC3064Q5: DC ~ 30 GHz, NF = 4 dB, Gain = 16 dB, P1dB = 24 dBm
- SAC3065Q4: DC ~ 40 GHz, Gain = 10 dB, P1dB = 18 dBm
- SAC3910: 22 ~ 38 GHz, Gain = 15 dB, P1dB = 24 dBm
- SAC3911: 24 ~ 40 GHz, Gain = 12 dB, P1dB = 15 dBm
- SAC3912: 20 ~ 38 GHz, Gain = 8 dB, P1dB = 18 dBm
- SAC3923: 1 ~ 20 GHz, Gain = 11 dB, P1dB = 28.5 dBm
- SAC3925: 26 ~ 38 GHz, Gain = 16 dB, P1dB = 26 dBm, PAE = 25%

# Some Connectorized Modules based on Our MMICs

22-26GHz 3w PA



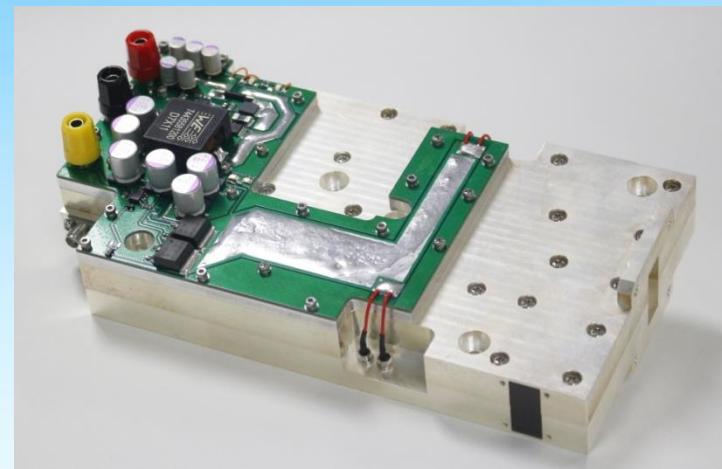
5.3-5.9GHz 4w PA



# Some Connectorized Modules based on Our MMICs



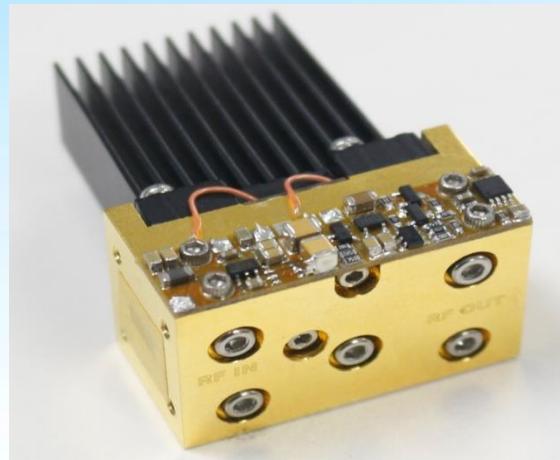
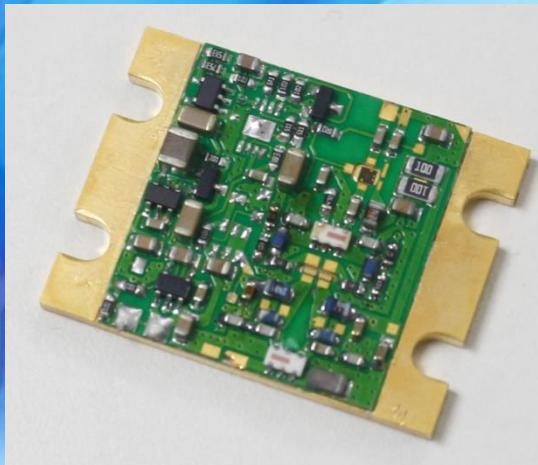
Ku 10W PA



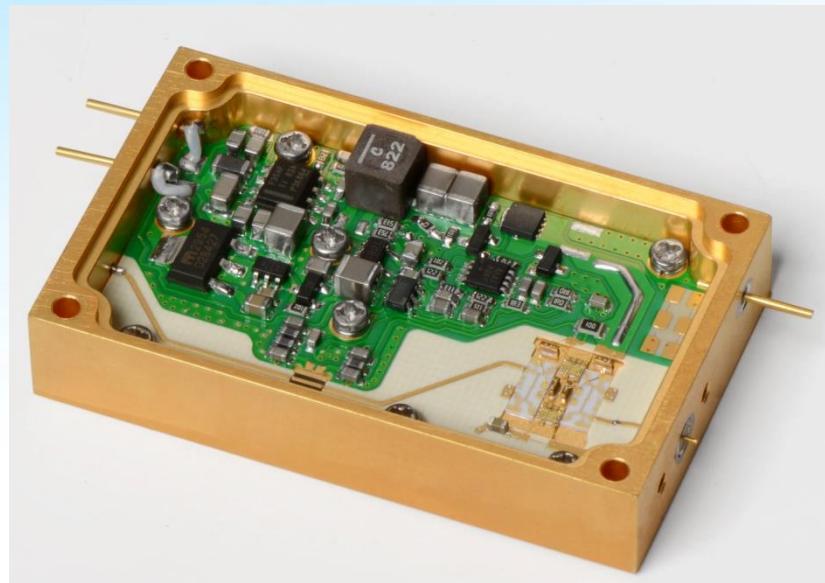
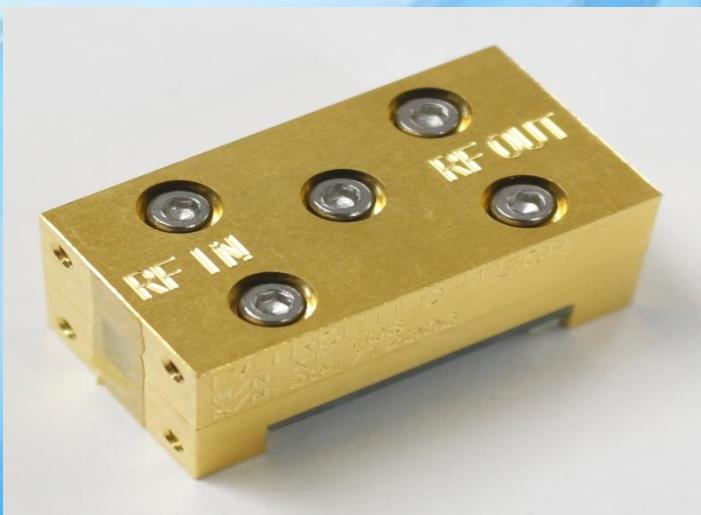
Ku 40W PA

# Some Connectorized Modules based on Our MMICs

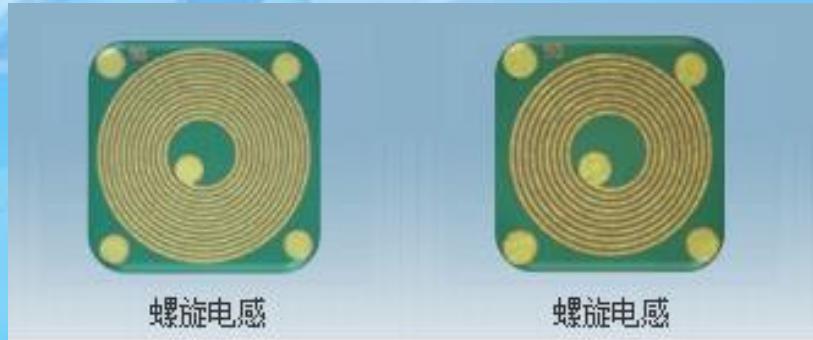
Based on our own MMIC chips, we can build most of standard modules including LNA, PA, Phase Shifter, Attenuator, Mixer, and Switch modules. We can also design and build custom modules and subsystems according to our customers' specific requirements.



# Some Connectorized Modules based on Our MMICs



# Spiral Inductors based on GaAs Technology



Model Number	Turns	Inductance (nH) (typ.)	Rs@DC (Ohm)	Rs@GHz (Ohm)	Q@GHz	Resonant Frequency (GHz)	Chip Size (m x mm)
SAC6005A	3.5	5	1.0	3.7@4.0	26.5@4.0	16.5	0.75×0.75
SAC6007P5A	4.5	7.5	1.3	6.0@4.0	27.0@4.0	12.8	0.80×0.80
SAC6010A	5.5	10	1.6	8.0@4.0	26.0@4.0	11.3	0.80×0.80
SAC6015A	6.5	15	2.1	5.6@4.0	26.5@4.0	8.5	0.80×0.80
SAC6020A	7.5	20	2.6	7.5@2.0	28.5@2.0	7.0	0.80×0.80
SAC6050A	9.5	50	5.1	10.6@1.0	28.5@1.5	2.8	0.95×0.95
SAC6090A	12.5	90	8.0	26.3@1.0	26.5@1.0	1.8	1.10×1.10
SAC6200A	17.5	200	14.0	30.0@1.0	23.0@1.0	1.0	1.37×1.37